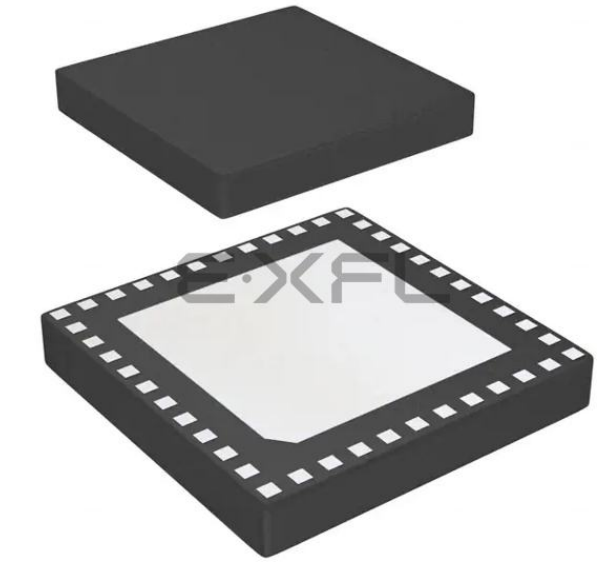
Microchip Technology - DSPIC33EP256MC204T-I/TL Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	35
Program Memory Size	256KB (85.5K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 9x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VFTLA Exposed Pad
Supplier Device Package	44-VTLA (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep256mc204t-i-tl

4.1.1 PROGRAM MEMORY ORGANIZATION

The program memory space is organized in word-addressable blocks. Although it is treated as 24 bits wide, it is more appropriate to think of each address of the program memory as a lower and upper word, with the upper byte of the upper word being unimplemented. The lower word always has an even address, while the upper word has an odd address (Figure 4-6).

Program memory addresses are always word-aligned on the lower word and addresses are incremented, or decremented by two, during code execution. This arrangement provides compatibility with data memory space addressing and makes data in the program memory space accessible.

4.1.2 INTERRUPT AND TRAP VECTORS

All dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices reserve the addresses between 0x000000 and 0x000200 for hard-coded program execution vectors. A hardware Reset vector is provided to redirect code execution from the default value of the PC on device Reset to the actual start of code. A GOTO instruction is programmed by the user application at address, 0x000000, of Flash memory, with the actual address for the start of code at address, 0x000002, of Flash memory.

A more detailed discussion of the Interrupt Vector Tables (IVTs) is provided in **Section 7.1 "Interrupt Vector Table"**.

FIGURE 4-6: PROGRAM MEMORY ORGANIZATION

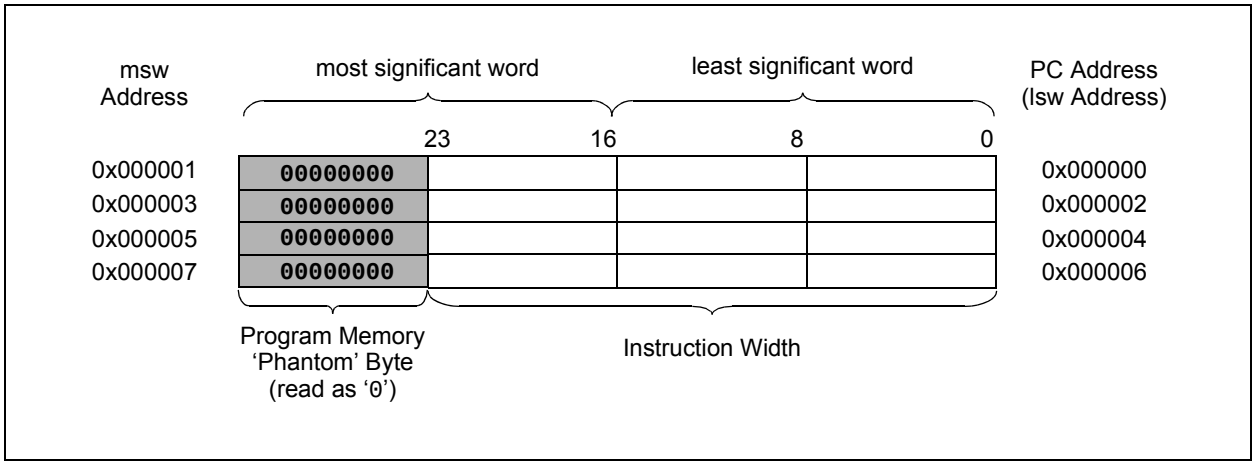
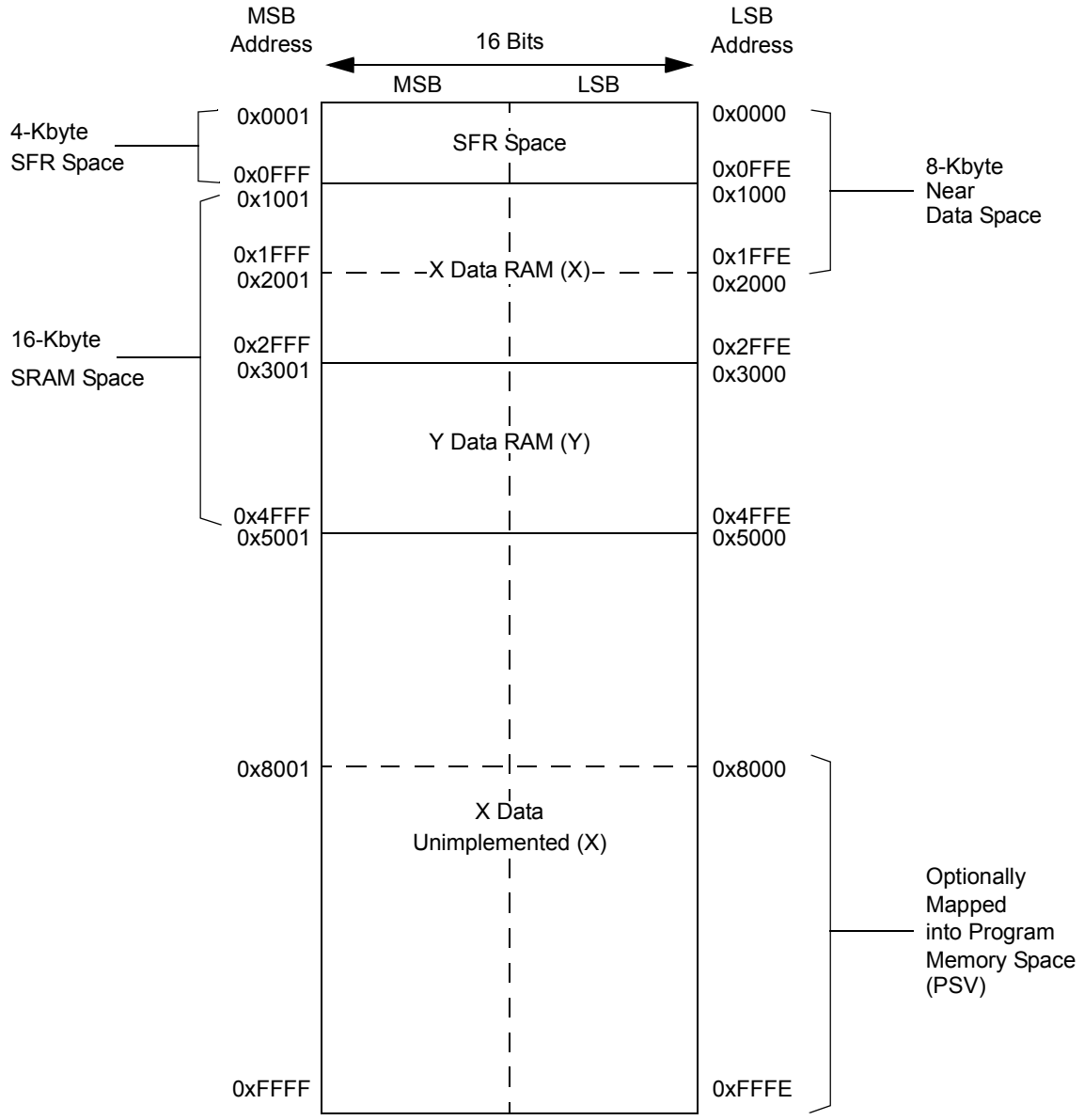
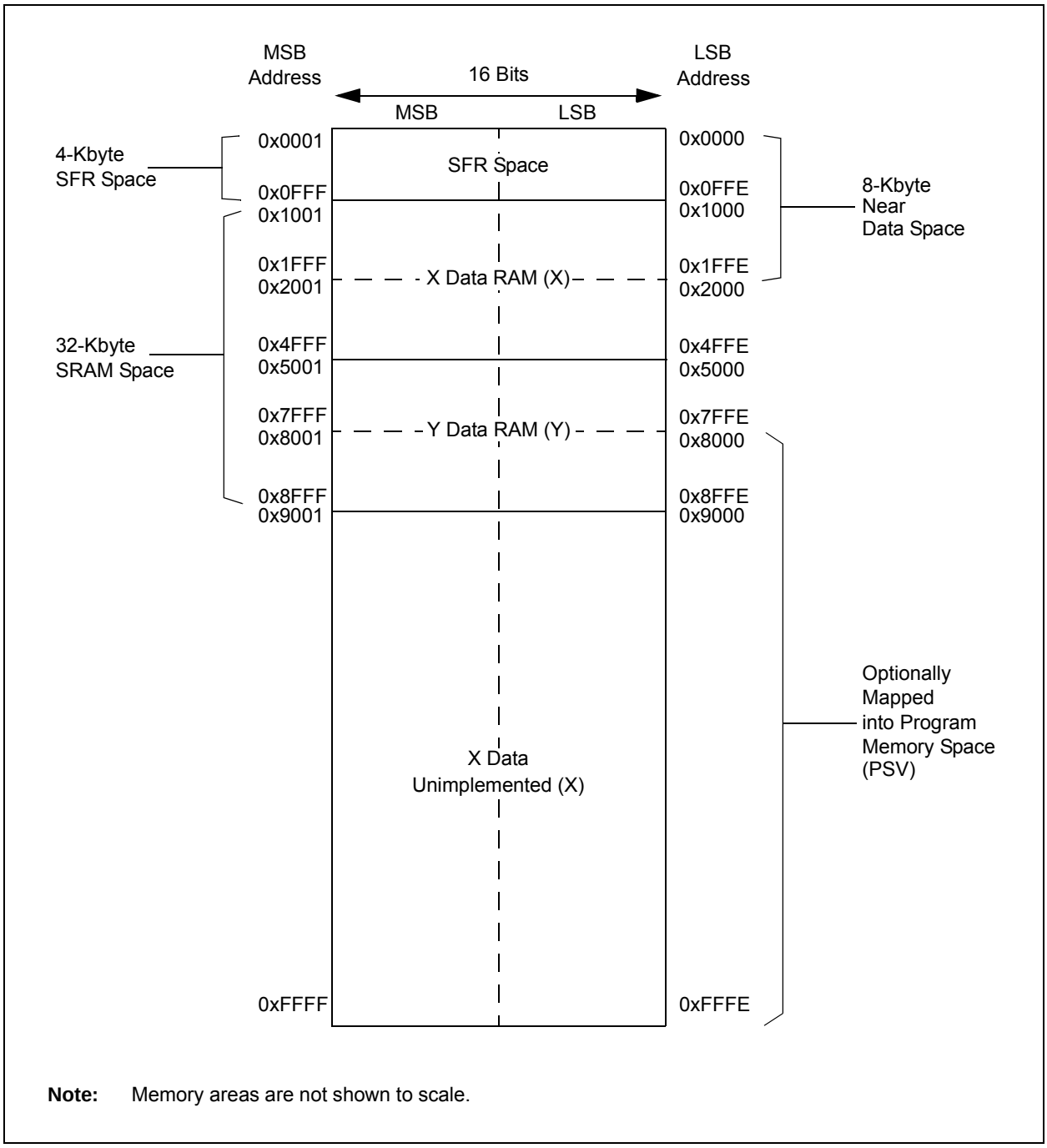


FIGURE 4-9: DATA MEMORY MAP FOR dsPIC33EP128MC20X/50X AND dsPIC33EP128GP50X DEVICES



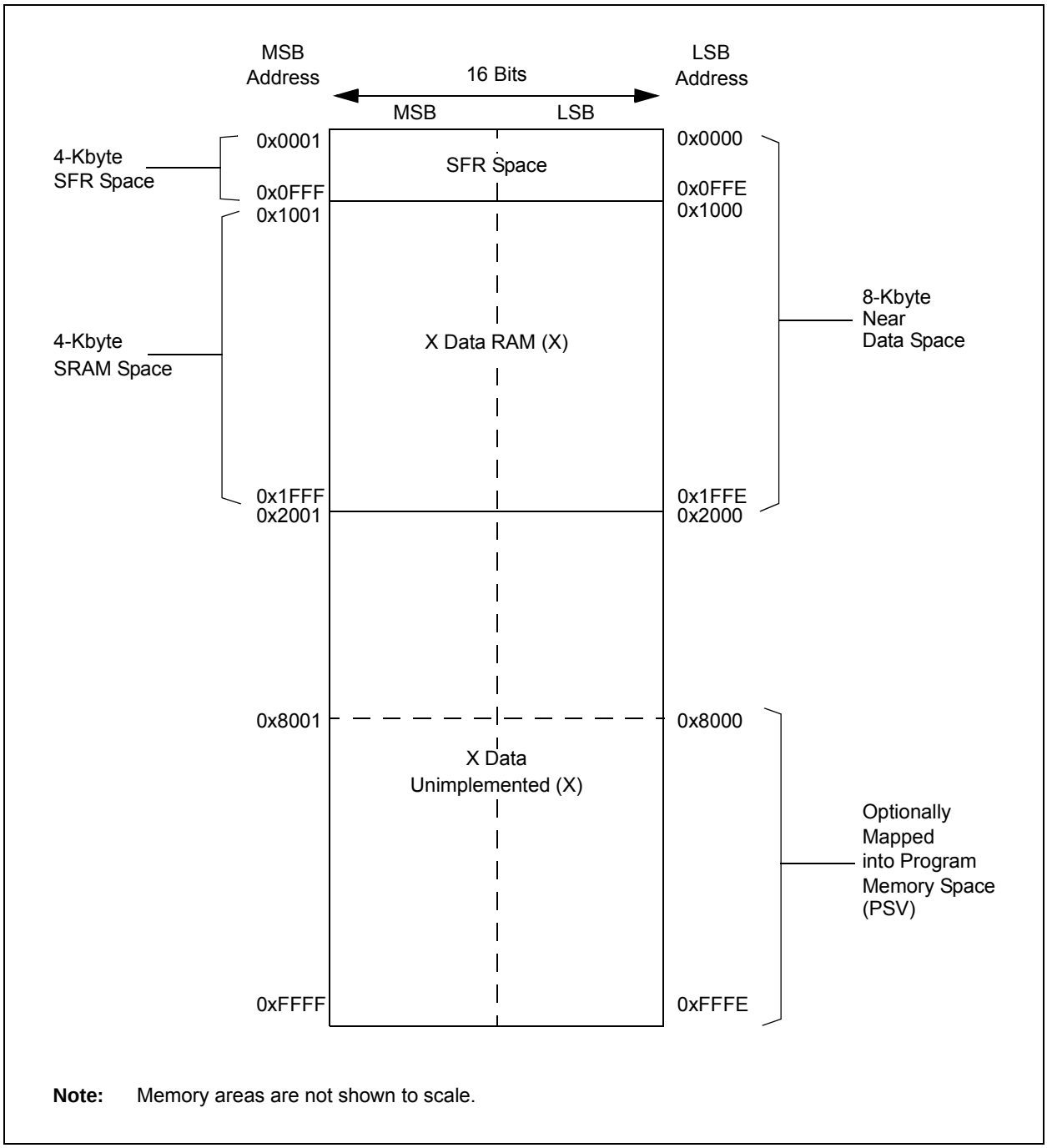
Note: Memory areas are not shown to scale.

FIGURE 4-10: DATA MEMORY MAP FOR dsPIC33EP256MC20X/50X AND dsPIC33EP256GP50X DEVICES



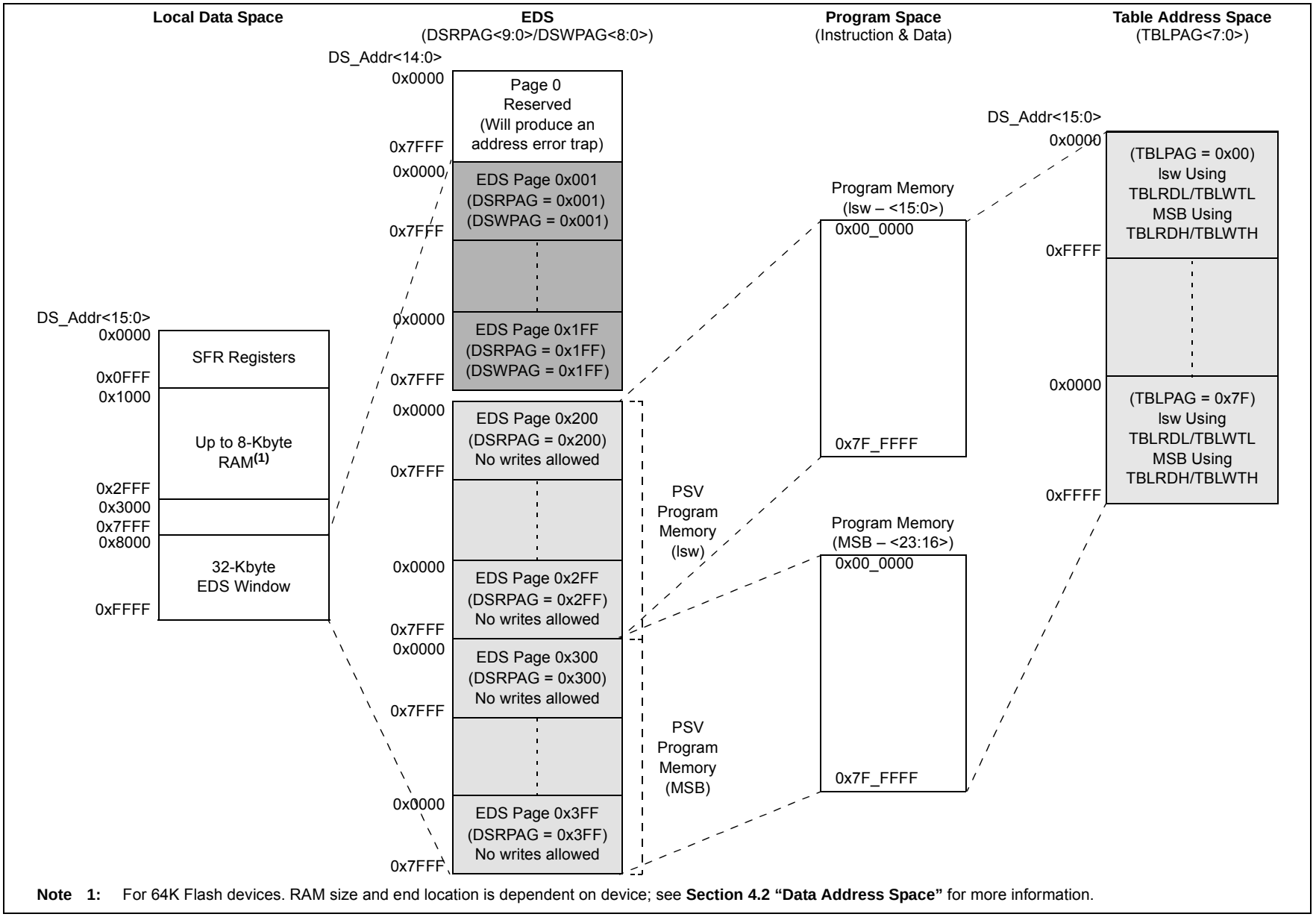
Note: Memory areas are not shown to scale.

FIGURE 4-12: DATA MEMORY MAP FOR PIC24EP32GP/MC20X/50X DEVICES



Note: Memory areas are not shown to scale.

EXAMPLE 4-3: PAGED DATA MEMORY SPACE



Note 1: For 64K Flash devices. RAM size and end location is dependent on device; see **Section 4.2 "Data Address Space"** for more information.

REGISTER 7-7: INTTREG: INTERRUPT CONTROL AND STATUS REGISTER

U-0	U-0	U-0	U-0	R-0	R-0	R-0	R-0
—	—	—	—	ILR3	ILR2	ILR1	ILR0
bit 15							bit 8

R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
VECNUM7	VECNUM6	VECNUM5	VECNUM4	VECNUM3	VECNUM2	VECNUM1	VECNUM0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-12 **Unimplemented:** Read as '0'

bit 11-8 **ILR<3:0>:** New CPU Interrupt Priority Level bits
1111 = CPU Interrupt Priority Level is 15
•
•
•
0001 = CPU Interrupt Priority Level is 1
0000 = CPU Interrupt Priority Level is 0

bit 7-0 **VECNUM<7:0>:** Vector Number of Pending Interrupt bits
11111111 = 255, Reserved; do not use
•
•
•
00001001 = 9, IC1 – Input Capture 1
00001000 = 8, INT0 – External Interrupt 0
00000111 = 7, Reserved; do not use
00000110 = 6, Generic soft error trap
00000101 = 5, DMAC error trap
00000100 = 4, Math error trap
00000011 = 3, Stack error trap
00000010 = 2, Generic hard trap
00000001 = 1, Address error trap
00000000 = 0, Oscillator fail trap

TABLE 11-2: INPUT PIN SELECTION FOR SELECTABLE INPUT SOURCES

Peripheral Pin Select Input Register Value	Input/ Output	Pin Assignment	Peripheral Pin Select Input Register Value	Input/ Output	Pin Assignment
000 0000	I	Vss	010 1101	I	RPI45
000 0001	I	C1OUT(1)	010 1110	I	RPI46
000 0010	I	C2OUT(1)	010 1111	I	RPI47
000 0011	I	C3OUT(1)	011 0000	—	—
000 0100	I	C4OUT(1)	011 0001	—	—
000 0101	—	—	011 0010	—	—
000 0110	I	PTGO30(1)	011 0011	I	RPI51
000 0111	I	PTGO31(1)	011 0100	I	RPI52
000 1000	I	FINDX1(1,2)	011 0101	I	RPI53
000 1001	I	FHOME1(1,2)	011 0110	I/O	RP54
000 1010	—	—	011 0111	I/O	RP55
000 1011	—	—	011 1000	I/O	RP56
000 1100	—	—	011 1001	I/O	RP57
000 1101	—	—	011 1010	I	RPI58
000 1110	—	—	011 1011	—	—
000 1111	—	—	011 1100	—	—
001 0000	—	—	011 1101	—	—
001 0001	—	—	011 1110	—	—
001 0010	—	—	011 1111	—	—
001 0011	—	—	100 0000	—	—
001 0100	I/O	RP20	100 0001	—	—
001 0101	—	—	100 0010	—	—
001 0110	—	—	100 0011	—	—
001 0111	—	—	100 0100	—	—
001 1000	I	RPI24	100 0101	—	—
001 1001	I	RPI25	100 0110	—	—
001 1010	—	—	100 0111	—	—
001 1011	I	RPI27	100 1000	—	—
001 1100	I	RPI28	100 1001	—	—
001 1101	—	—	100 1010	—	—
001 1110	—	—	100 1011	—	—
001 1111	—	—	100 1100	—	—
010 0000	I	RPI32	100 1101	—	—
010 0001	I	RPI33	100 1110	—	—
010 0010	I	RPI34	100 1111	—	—
010 0011	I/O	RP35	101 0000	—	—
010 0100	I/O	RP36	101 0001	—	—
010 0101	I/O	RP37	101 0010	—	—
010 0110	I/O	RP38	101 0011	—	—
010 0111	I/O	RP39	101 0100	—	—

Legend: Shaded rows indicate PPS Input register values that are unimplemented.

Note 1: See **Section 11.4.4.1 “Virtual Connections”** for more information on selecting this pin assignment.

2: These inputs are available on dsPIC33EPXXXGP/MC50X devices only.

REGISTER 11-20: RPOR2: PERIPHERAL PIN SELECT OUTPUT REGISTER 2

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP39R<5:0>					
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP38R<5:0>					
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13-8 **RP39R<5:0>:** Peripheral Output Function is Assigned to RP39 Output Pin bits (see Table 11-3 for peripheral function numbers)

bit 7-6 **Unimplemented:** Read as '0'

bit 5-0 **RP38R<5:0>:** Peripheral Output Function is Assigned to RP38 Output Pin bits (see Table 11-3 for peripheral function numbers)

REGISTER 11-21: RPOR3: PERIPHERAL PIN SELECT OUTPUT REGISTER 3

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP41R<5:0>					
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP40R<5:0>					
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13-8 **RP41R<5:0>:** Peripheral Output Function is Assigned to RP41 Output Pin bits (see Table 11-3 for peripheral function numbers)

bit 7-6 **Unimplemented:** Read as '0'

bit 5-0 **RP40R<5:0>:** Peripheral Output Function is Assigned to RP40 Output Pin bits (see Table 11-3 for peripheral function numbers)

NOTES:

REGISTER 21-16: CxRXFnSID: ECANx ACCEPTANCE FILTER n STANDARD IDENTIFIER REGISTER (n = 0-15)

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
SID10	SID9	SID8	SID7	SID6	SID5	SID4	SID3
bit 15							bit 8

R/W-x	R/W-x	R/W-x	U-0	R/W-x	U-0	R/W-x	R/W-x
SID2	SID1	SID0	—	EXIDE	—	EID17	EID16
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-5 **SID<10:0>:** Standard Identifier bits
1 = Message address bit, SIDx, must be '1' to match filter
0 = Message address bit, SIDx, must be '0' to match filter

bit 4 **Unimplemented:** Read as '0'

bit 3 **EXIDE:** Extended Identifier Enable bit
If MIDE = 1:
1 = Matches only messages with Extended Identifier addresses
0 = Matches only messages with Standard Identifier addresses
If MIDE = 0:
Ignores EXIDE bit.

bit 2 **Unimplemented:** Read as '0'

bit 1-0 **EID<17:16>:** Extended Identifier bits
1 = Message address bit, EIDx, must be '1' to match filter
0 = Message address bit, EIDx, must be '0' to match filter

REGISTER 23-2: AD1CON2: ADC1 CONTROL REGISTER 2 (CONTINUED)

bit 1 **BUFM:** Buffer Fill Mode Select bit

1 = Starts the buffer filling the first half of the buffer on the first interrupt and the second half of the buffer on next interrupt

0 = Always starts filling the buffer from the start address.

bit 0 **ALTS:** Alternate Input Sample Mode Select bit

1 = Uses channel input selects for Sample MUXA on first sample and Sample MUXB on next sample

0 = Always uses channel input selects for Sample MUXA

25.0 OP AMP/COMPARATOR MODULE

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Op Amp/Comparator"** (DS70357) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices contain up to four comparators, which can be configured in various ways. Comparators, CMP1, CMP2 and CMP3, also have the option to be configured as op amps, with the output being brought to an external pin for gain/filtering connections. As shown in Figure 25-1, individual comparator options are specified by the comparator module's Special Function Register (SFR) control bits.

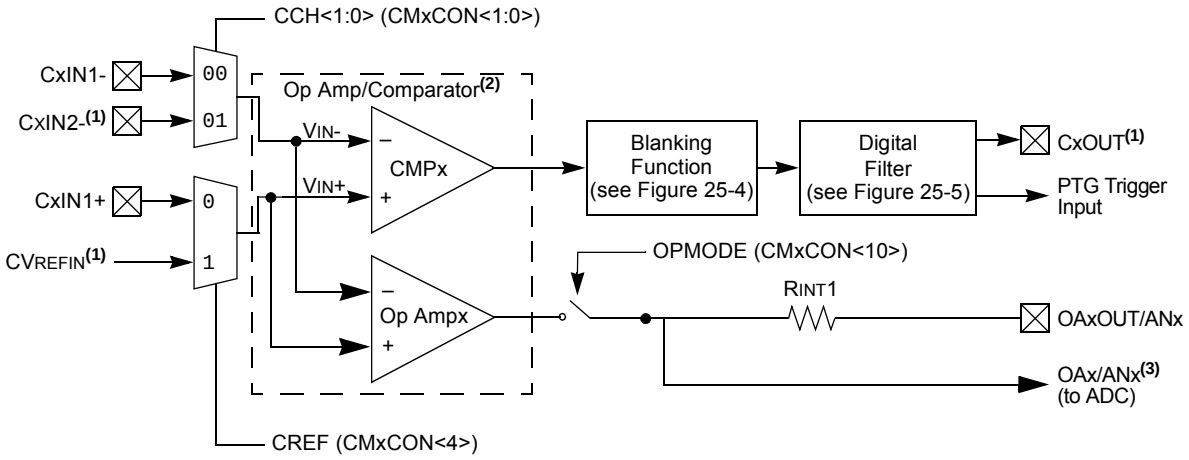
Note: Op Amp/Comparator 3 is not available on the dsPIC33EPXXXGP502/MC502/MC202 and PIC24EP256GP/MC202 (28-pin) devices.

These options allow users to:

- Select the edge for trigger and interrupt generation
- Configure the comparator voltage reference
- Configure output blanking and masking
- Configure as a comparator or op amp (CMP1, CMP2 and CMP3 only)

Note: Not all op amp/comparator input/output connections are available on all devices. See the **"Pin Diagrams"** section for available connections.

FIGURE 25-1: OP AMP/COMPARATOR x MODULE BLOCK DIAGRAM (MODULES 1, 2 AND 3)



Note 1: This input/output is not available as a selection when configured as an op amp (OPMODE (CMxCON<10>) = 1).

2: This module can be configured either as an op amp or a comparator using the OPMODE bit.

3: When configured as an op amp (OPMODE = 1), the ADC samples the op amp output; otherwise, the ADC samples the ANx pin.

REGISTER 25-3: CM4CON: COMPARATOR 4 CONTROL REGISTER

R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	R/W-0	R/W-0
CON	COE	CPOL	—	—	—	CEVT	COUT
bit 15							bit 8

R/W-0	R/W-0	U-0	R/W-0	U-0	U-0	R/W-0	R/W-0
EVPOL1	EVPOL0	—	CREF(1)	—	—	CCH1(1)	CCH0(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **CON:** Comparator Enable bit
1 = Comparator is enabled
0 = Comparator is disabled

bit 14 **COE:** Comparator Output Enable bit
1 = Comparator output is present on the CxOUT pin
0 = Comparator output is internal only

bit 13 **CPOL:** Comparator Output Polarity Select bit
1 = Comparator output is inverted
0 = Comparator output is not inverted

bit 12-10 **Unimplemented:** Read as '0'

bit 9 **CEVT:** Comparator Event bit
1 = Comparator event according to EVPOL<1:0> settings occurred; disables future triggers and interrupts until the bit is cleared
0 = Comparator event did not occur

bit 8 **COUT:** Comparator Output bit
When CPOL = 0 (non-inverted polarity):
1 = VIN+ > VIN-
0 = VIN+ < VIN-
When CPOL = 1 (inverted polarity):
1 = VIN+ < VIN-
0 = VIN+ > VIN-

bit 7-6 **EVPOL<1:0>:** Trigger/Event/Interrupt Polarity Select bits
11 = Trigger/event/interrupt generated on any change of the comparator output (while CEVT = 0)
10 = Trigger/event/interrupt generated only on high-to-low transition of the polarity selected comparator output (while CEVT = 0)
If CPOL = 1 (inverted polarity):
Low-to-high transition of the comparator output.
If CPOL = 0 (non-inverted polarity):
High-to-low transition of the comparator output.
01 = Trigger/event/interrupt generated only on low-to-high transition of the polarity selected comparator output (while CEVT = 0)
If CPOL = 1 (inverted polarity):
High-to-low transition of the comparator output.
If CPOL = 0 (non-inverted polarity):
Low-to-high transition of the comparator output.
00 = Trigger/event/interrupt generation is disabled

Note 1: Inputs that are selected and not available will be tied to VSS. See the **"Pin Diagrams"** section for available inputs for each package.

NOTES:

TABLE 30-8: DC CHARACTERISTICS: POWER-DOWN CURRENT (I_{PD})

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended		
Parameter No.	**Typ.**	**Max.**	**Units**	**Conditions**	
Power-Down Current (I_{PD})(1) – dsPIC33EP32GP50X, dsPIC33EP32MC20X/50X and PIC24EP32GP/MC20X					
DC60d	30	100	μA	-40°C	3.3V
DC60a	35	100	μA	+25°C	
DC60b	150	200	μA	+85°C	
DC60c	250	500	μA	+125°C	
Power-Down Current (I_{PD})(1) – dsPIC33EP64GP50X, dsPIC33EP64MC20X/50X and PIC24EP64GP/MC20X					
DC60d	25	100	μA	-40°C	3.3V
DC60a	30	100	μA	+25°C	
DC60b	150	350	μA	+85°C	
DC60c	350	800	μA	+125°C	
Power-Down Current (I_{PD})(1) – dsPIC33EP128GP50X, dsPIC33EP128MC20X/50X and PIC24EP128GP/MC20X					
DC60d	30	100	μA	-40°C	3.3V
DC60a	35	100	μA	+25°C	
DC60b	150	350	μA	+85°C	
DC60c	550	1000	μA	+125°C	
Power-Down Current (I_{PD})(1) – dsPIC33EP256GP50X, dsPIC33EP256MC20X/50X and PIC24EP256GP/MC20X					
DC60d	35	100	μA	-40°C	3.3V
DC60a	40	100	μA	+25°C	
DC60b	250	450	μA	+85°C	
DC60c	1000	1200	μA	+125°C	
Power-Down Current (I_{PD})(1) – dsPIC33EP512GP50X, dsPIC33EP512MC20X/50X and PIC24EP512GP/MC20X					
DC60d	40	100	μA	-40°C	3.3V
DC60a	45	100	μA	+25°C	
DC60b	350	800	μA	+85°C	
DC60c	1100	1500	μA	+125°C	

Note 1: I_{PD} (Sleep) current is measured as follows:

- CPU core is off, oscillator is configured in EC mode and external clock is active; OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as inputs and pulled to V_{SS}
- $\overline{MCLR}$ = V_{DD}, WDT and FSCM are disabled
- All peripheral modules are disabled (PMDx bits are all set)
- The VREGS bit (RCON<8>) = 0 (i.e., core regulator is set to standby while the device is in Sleep mode)
- The VREGSF bit (RCON<11>) = 0 (i.e., Flash regulator is set to standby while the device is in Sleep mode)
- JTAG is disabled

TABLE 30-40: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 0, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK2 Input Frequency	—	—	11	MHz	**(Note 3)**
SP72	TscF	SCK2 Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCK2 Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO2 Data Output Fall Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP31	TdoR	SDO2 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO2 Data Output Valid after SCK2 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO2 Data Output Setup to First SCK2 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SS2}$ ↓ to SCK2 ↑ or SCK2 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SS2}$ ↑ to SDO2 Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH TscL2ssH	$\overline{SS2}$ ↑ after SCK2 Edge	1.5 TCY + 40	—	—	ns	**(Note 4)**

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK2 is 91 ns. Therefore, the SCK2 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI2 pins.

TABLE 30-53: OP AMP/COMPARATOR SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)(1) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
Comparator AC Characteristics							
CM10	TRESP	Response Time(3)	—	19	—	ns	V+ input step of 100 mV, V- input held at VDD/2
CM11	TMC2OV	Comparator Mode Change to Output Valid	—	—	10	µs	
Comparator DC Characteristics							
CM30	VOFFSET	Comparator Offset Voltage	—	±10	40	mV	
CM31	VHYST	Input Hysteresis Voltage(3)	—	30	—	mV	
CM32	TRISE/ TFALL	Comparator Output Rise/ Fall Time(3)	—	20	—	ns	1 pF load capacitance on input
CM33	VGAIN	Open-Loop Voltage Gain(3)	—	90	—	db	
CM34	VICM	Input Common-Mode Voltage	AVSS	—	AVDD	V	
Op Amp AC Characteristics							
CM20	SR	Slew Rate(3)	—	9	—	V/µs	10 pF load
CM21a	PM	Phase Margin (Configuration A)(3,4)	—	55	—	Degree	G = 100V/V; 10 pF load
CM21b	PM	Phase Margin (Configuration B)(3,5)	—	40	—	Degree	G = 100V/V; 10 pF load
CM22	GM	Gain Margin(3)	—	20	—	db	G = 100V/V; 10 pF load
CM23a	GBW	Gain Bandwidth (Configuration A)(3,4)	—	10	—	MHz	10 pF load
CM23b	GBW	Gain Bandwidth (Configuration B)(3,5)	—	6	—	MHz	10 pF load

Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

2: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.

3: Parameter is characterized but not tested in manufacturing.

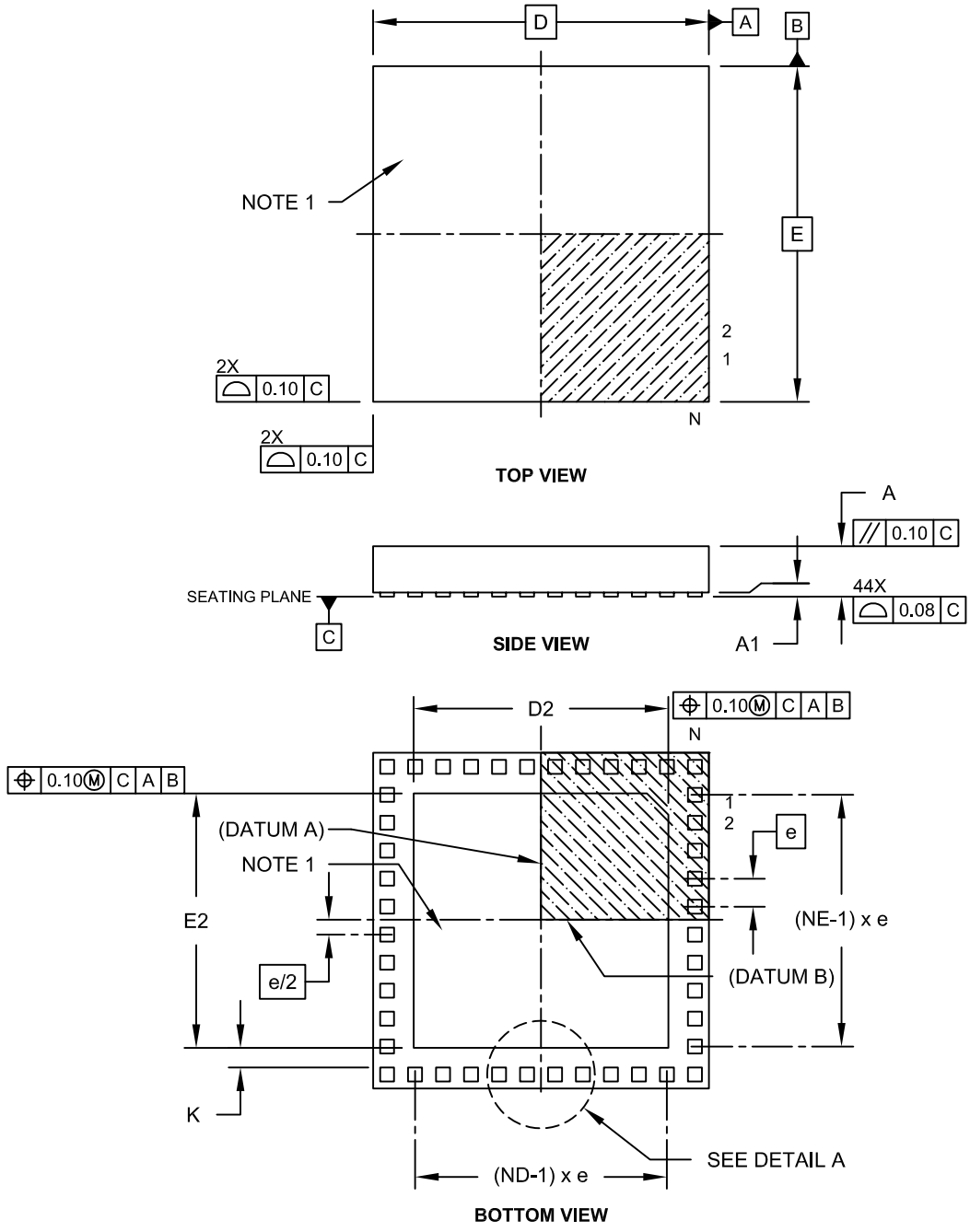
4: See Figure 25-6 for configuration information.

5: See Figure 25-7 for configuration information.

6: Resistances can vary by ±10% between op amps.

44-Terminal Very Thin Leadless Array Package (TL) – 6x6x0.9 mm Body With Exposed Pad [VTLA]

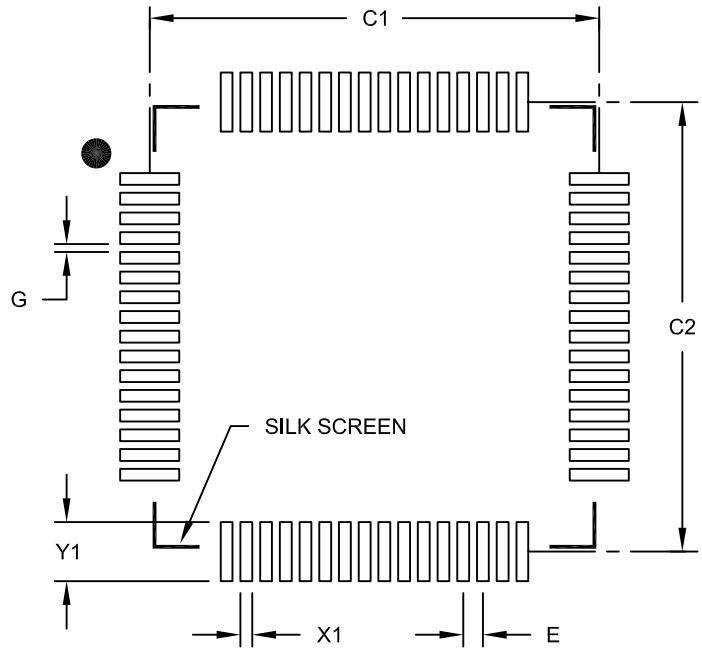
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-157C Sheet 1 of 2

64-Lead Plastic Thin Quad Flatpack (PT) 10x10x1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Contact Pad Spacing	C1		11.40	
Contact Pad Spacing	C2		11.40	
Contact Pad Width (X64)	X1			0.30
Contact Pad Length (X64)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2085B

TABLE A-5: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 30.0 "Electrical Characteristics"	• Throughout: qualifies all footnotes relating to the operation of analog modules below VDDMIN (replaces "will have" with "may have") • Throughout: changes all references of SPI timing parameter symbol "TscP" to "FscP" • Table 30-1: changes VDD range to 3.0V to 3.6V • Table 30-4: removes Parameter DC12 (RAM Retention Voltage) • Table 30-7: updates Maximum values at 10 and 20 MIPS • Table 30-8: adds Maximum IPD values, and removes all ΔIWDT entries • Adds new Table 30-9 (Watchdog Timer Delta Current) with consolidated values removed from Table 30-8. All subsequent tables are renumbered accordingly. • Table 30-10: adds footnote for all parameters for 1:2 Doze ratio • Table 30-11: - changes Minimum and Maximum values for D120 and D130 - adds Minimum and Maximum values for D131 - adds Minimum and Maximum values for D150 through D156, and removes Typical values • Table 30-12: - reformats table for readability - changes IOL conditions for DO10 • Table 30-14: adds footnote to D135 • Table 30-17: changes Minimum and Maximum values for OS30 • Table 30-19: - splits temperature range and adds new values for F20a - reduces temperature range for F20b to extended temperatures only • Table 30-20: - splits temperature range and adds new values for F21a - reduces temperature range for F20b to extended temperatures only • Table 30-53: - adds Maximum value to CM30 - adds footnote ("Parameter characterized...") to multiple parameters • Table 30-55: adds Minimum and Maximum values for all CTMUI specifications, and removes Typical values • Table 30-57: adds new footnote to AD09 • Table 30-58: - removes all specifications for accuracy with external voltage references - removes Typical values for AD23a and AD24a - replaces Minimum and Maximum values for AD21a, AD22a, AD23a and AD24a with new values, split by Industrial and Extended temperatures - removes Maximum value of AD30 - removes Minimum values from AD31a and AD32a - adds or changes Typical values for AD30, AD31a, AD32a and AD33a • Table 30-59: - removes all specifications for accuracy with external voltage references - removes Maximum value of AD30 - removes Typical values for AD23b and AD24b - replaces Minimum and Maximum values for AD21b, AD22b, AD23b and AD24b with new values, split by Industrial and Extended temperatures - removes Minimum and Maximum values from AD31b, AD32b, AD33b and AD34b - adds or changes Typical values for AD30, AD31a, AD32a and AD33a • Table 30-61: Adds footnote to AD51
Section 32.0 "DC and AC Device Characteristics Graphs"	• Updates Figure 32-6 (Typical IDD @ 3.3V) with individual current vs. processor speed curves for the different program memory sizes
Section 33.0 "Packaging Information"	• Replaces drawing C04-149C (64-pin QFN, 7.15 x 7.15 exposed pad) with C04-154A (64-pin QFN, 5.4 x 5.4 exposed pad)